

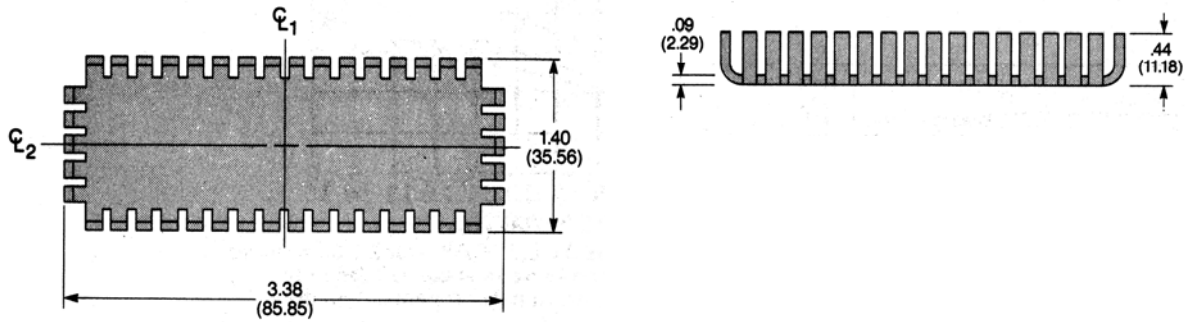
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

UP10 for Single TO-3 Outline

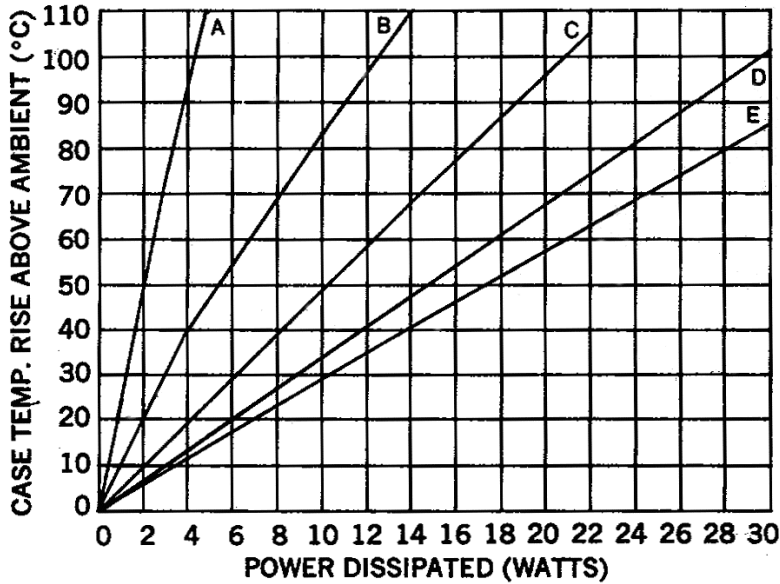
Natural Conv. (°C/W): 8.7

Forced Air (°C/W): 2.9

Mounting Envelope: 3.38" x 1.40" x .44"



UP10-TO3-CB w/2N3055 (TO-3) TRANSISTOR



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

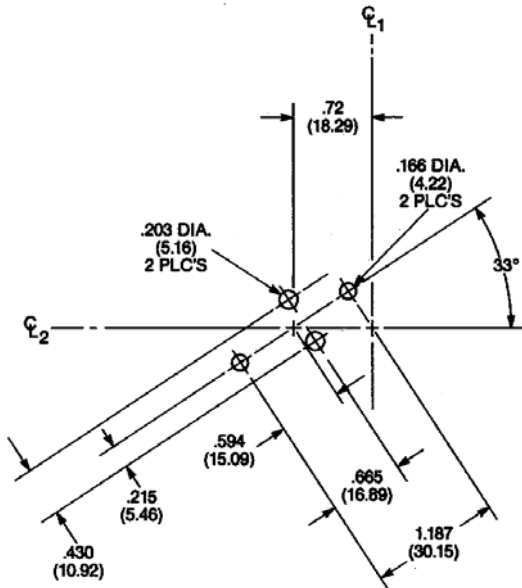
- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 0.4 °C/watt for unplated part in natural convection only.

Ordering Information

CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
UP10-TO3-U	UP10-TO3-CB	UP10-TO3-B	TO-3	37	24.0

HOLE PATTERNS

37. Hole pattern no. 432 accommodates TO-3s. Available in UP10 series heat dissipators only.



CTS IERC, Heat Sinks and Thermal Management Solutions

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